SMBJ3.3A

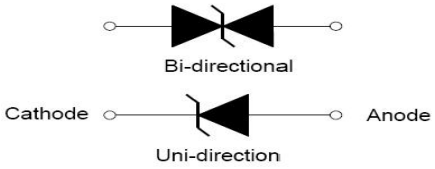
Transient Voltage Suppressor

»Features

- Excellent clamping capability
- Low leakage current
- Low capacitance
- High surge capability
- Glass passivated chip
- Epoxy resin package
- Built-in strain relief
- Will not fatigue
- RoHS Compliant
- Fast response time:
  typically less than 1.0ps from 0 Volts to V_{BR} min



SMB (DO-214AA)



»Mechanical Characteristics

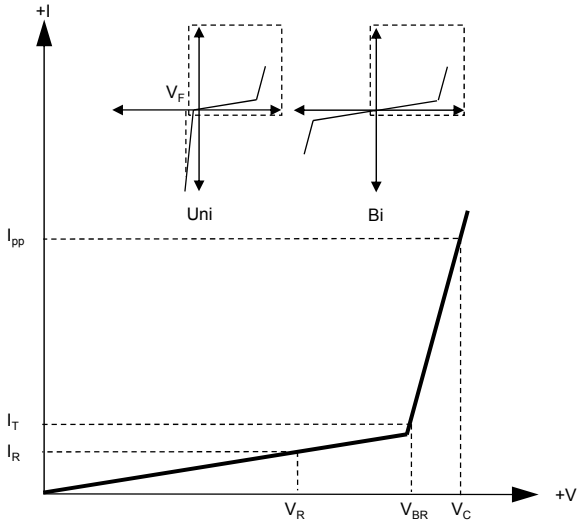
- Package: SMB plastic package.
- Lead Finish: Matte Tin
- Case Material: Epoxy Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020

»Applications

- Telecom
- Computer
- Industrial electronic
- Consumer electronic

»Electrical Parameters

Parameter	Definition
C_J	Junction Capacitance - typical capacitance measured with 0V or V_R bias
I_{PP}	Peak Pulse Current - maximum rated peak impulse current
V_C	Clamping Voltage - Peak voltage measured across the suppressor at a specified Ippm (peak impulse current)
V_{BR}	Breakdown Voltage - Maximum voltage that flows though the TVS at a specified test current (I_T)
I_R	Leakage Current - maximum peak off-state current measured at V_R
V_R	Peak Off-state Voltage - maximum voltage that can be applied while maintaining off state



»Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
SMB	Tape/Reel,13" reel	3000	EIA-481-1
	Tape/Reel,7" reel	500	EIA-481-1

»Absolute Maximum Ratings (T_A=25℃ unless otherwise noted)

Parameter	Symbol	Value	Units
Peak Pulse Power Dissipation on 10/1000 us Waveform (Note 1, 2, FIG.1)	P_{PPM}	Min 600	W
Power Dissipation on Infinite Heat Sink at T_L=50°C	P_D	5	W
Peak Pulse Current of on 10/1000us Waveform (Note 1, FIG.3)	I_{PPM}	See Table 1	A
Peak Forward Surge Current, 8.3ms Single Half Sine-Wave (Note 2. 3)	I_{FSM}	78.9	A
Operating Junction Temperature Range	T_J	-55 to 150	°C
Storage Temperature Range	T_{STG}	-55 to 150	°C

Notes: 1. Non-repetitive current pulse, per Fig.3 and derated above T_A=25°C per Fig.2.
2. Mounted on 5.0x5.0mm^2 (0.03mm thick) Copper Pads to each terminal.
3. Measured on 8.3ms single half sine-wave, or equivalent square wave, for Unidirectional device only.

»Electrical Characteristics (T_A=25°C unless otherwise noted)

Type Number	Marking	Reverse Stand-Off Voltage	Breakdown Voltage Min. @I_T	Breakdown Voltage Max. @ I_T	Test Current	Maximum Clamping Voltage @I_{PP}	Peak Pulse Current	Reverse Leakage @V_{RMW}
(Uni)	(Uni)	V_{RMW}(V)	$V_{BR\ MIN}$(V)	$V_{BR\ MAX}$(V)	I_T (mA)	V_C(V)	I_{PP}(A)	I_R(uA)
SMBJ3.3A	SMBJ 3.3A	3.3	5.0	5.8	10	7.6	78.9	100

»Rating And Characteristic Curves (T_A=25°C unless otherwise noted)

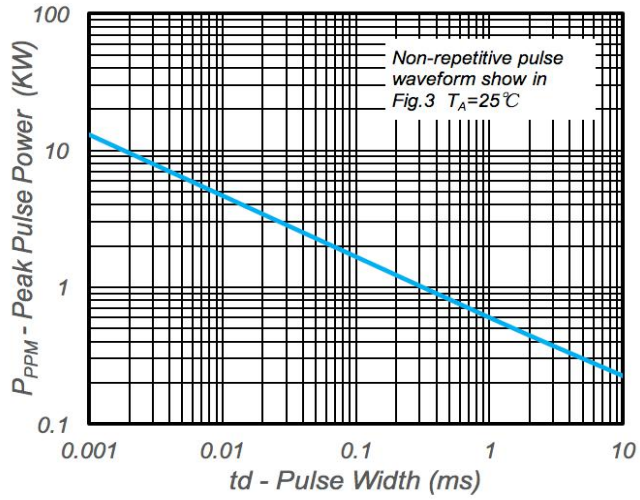


Fig.1 - Peak Pulse Power Rating

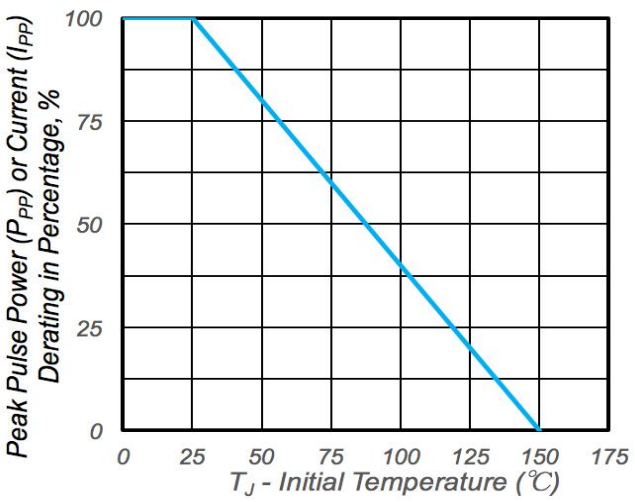


Fig.2 - Pulse Derating Cure

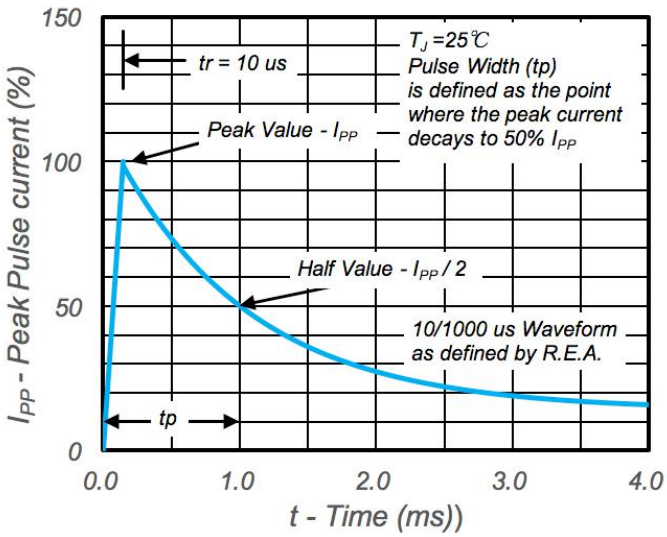


Fig.3 - Pulse Waveform

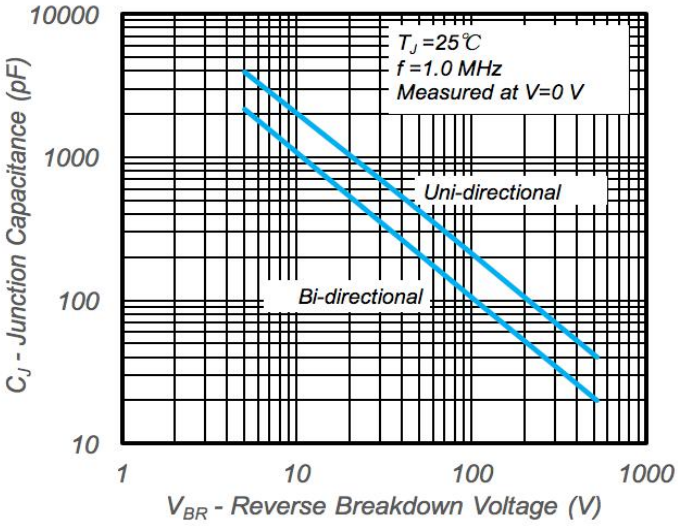
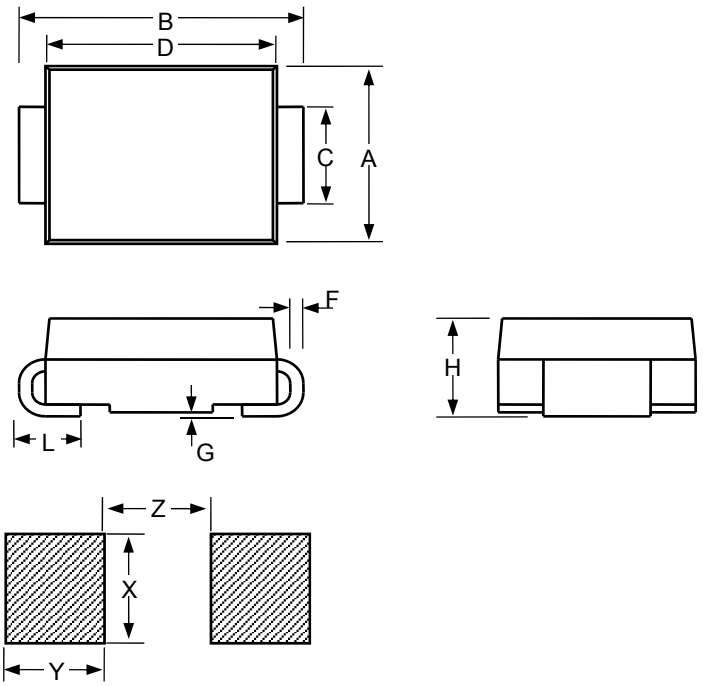


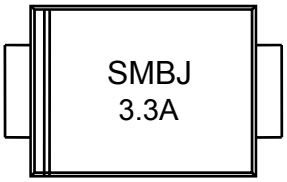
Fig.4 - Typical Junction Capacitance

»Package Dimensions

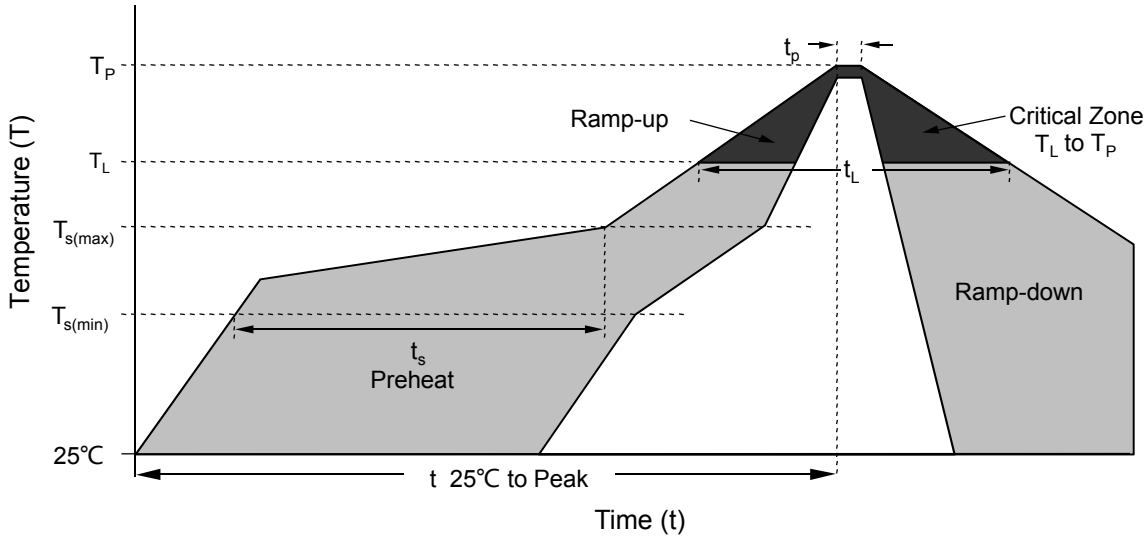


SMB						
Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.134	0.144	0.155	3.4	3.67	3.94
B	0.205	0.213	0.22	5.21	5.4	5.59
C	0.075	0.079	0.083	1.9	2	2.1
D	0.169		0.185	4.3		4.7
F	0.006		0.012	0.152		0.305
G	-		0.008	-		0.203
H	0.085	0.091	0.096	2.15	2.3	2.45
L	0.03		0.06	0.76		1.52
X		0.11			2.8	
Y		0.079			2	
Z		0.079			2	

»Marking Information

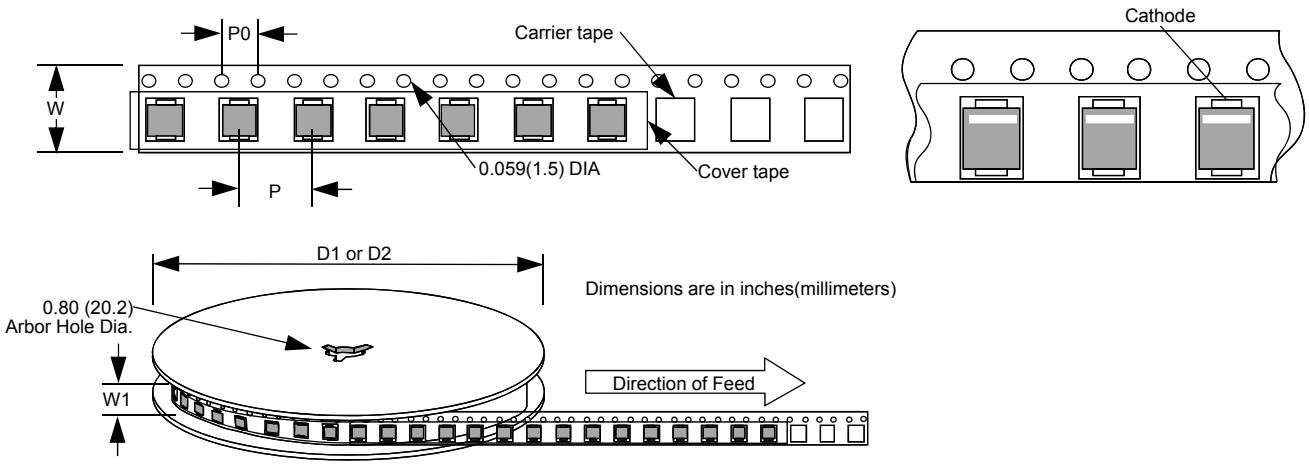


»Soldering Parameters



Reflow Condition		Lead-free assembly
Pre Heat	- Temperature Min ($T_{s(min)}$)	150°C
	- Temperature Max ($T_{s(max)}$)	200°C
	- Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{S(max)}$ to TL - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Time (t_L)	60 – 150 secs
Peak Temperature (T_P)		$260^{+0/-5\ °C}$
Time within 5°C of actual peak Temperature (t_p)		20 – 40 secs
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (t)		8 minutes Max.
Do not exceed		260°C

»Tape and Reel Specification



Dimension	Inches			Millimeters		
	MIN	NOM	MAX	MIN	NOM	MAX
P		0.315			8	
P0		0.157			4	
W		0.472			12	
W1		0.492			12.5	
D1		7			177.8	
D2		13			330.2	